



(0.635 mm) .025"



HIGH-SPEED COMBO RF & POWER

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?QMS

Insulator Material:

Liquid Crystal Polymer Terminal & Ground Plane Material:

Phosphor Bronze

Plating: Au over 50 μ" (1.27 μm) Ni (Tin on Ground Plane Tail) Current Rating: Signal Contact: 2.6 A per pin

(2 pins powered) Power Contact: 4.0 A per pin

(4 pins powered per end) Ground Plane: 15.7 A per ground plane

Voltage Rating:
300 VAC mated with QFS
Operating Temp:
-55 °C to +125 °C

RoHS Compliant: Yes

PROCESSING

Lead-Free Solderable:

SMT Lead Coplanarity: (0.10 mm) .004" max (026-078) Board Stacking:

For applications requiring more than two connectors per board, contact ipg@samtec.com

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality

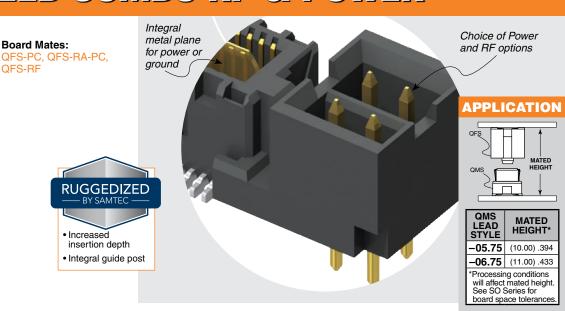


ALSO AVAILABLE (MOQ Required)

- · Other platings
- Differential Pairs
- Retention Pins
- 8 Power Pins/End for (1.60 mm) 0.62" thick board
- 4 or 8 Power Pins/End for (2.36 mm) .093" thick board
- 2 RF Connectors/End
- · Hot Pluggable

Contact Samtec.

Some lengths, styles and options are non-standard, non-returnable.



LEAD

STYLE

Α

(5.38)

.212 (6.35)



NO. OF PINS

PER ROW

QMS

PLATING

OPTION

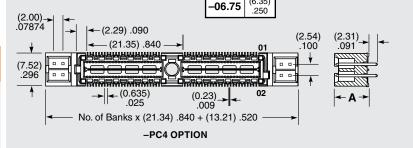
= 10 μ" (0.25 μm) Gold on Signal Pins and Ground Plane (Tin on Signal Pin tails, and Ground Plane tails)

-PC4 = 4 Power Pins per End for (1.60 mm) .062" thick Board (N/A with -RF1)

END

OPTION

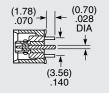
-RF1 = One RF Plug per End (-05.75 only, not available with -PC4)



LEAD STYLE

-05.75

No. of Banks x (21.34) .840 + (14.86) .585 01 02 -RF1 OPTION



SOLUTIONS

OTHER

See SO Series for precision machined standoffs.

Due to technical progress, all designs, specifications and components are subject to change without notice. WWW.SAMTEC.COM